

Listing f Claims:

1. (ORIGINAL) A bonded structure, comprising:
 - an integrated circuit element having input/output pads;
 - a substrate having input/output pads; and
 - a plurality of physical and electrical connections between said integrated circuit element input/output pads and said substrate input/output pads wherein each said connection includes a composite bump comprised of a polymer body and a conductive metal coating covering said polymer body, and wherein said composite bump is deformed when said connection is formed.
2. (ORIGINAL) The bonded structure of claim 1 wherein said polymer is polyamic acid polyimide.
3. (ORIGINAL) The bonded structure of claim 1 wherein said conductive metal coating is comprised of an adhesion layer, a barrier layer and a conductor layer.
4. (ORIGINAL) The bonded structure of claim 1 wherein said composite bumps are formed on said integrated circuit element input/output pads prior to formation of said connection.
5. (ORIGINAL) The bonded structure of claim 1 wherein said composite bumps are formed on said substrate input/output pads prior to formation of said connection.

6. (ORIGINAL) The bonded structure of claim 1 wherein said composite bumps are formed on both said integrated circuit element input/output pads and substrate input/output pads prior to formation of said connection.